

4

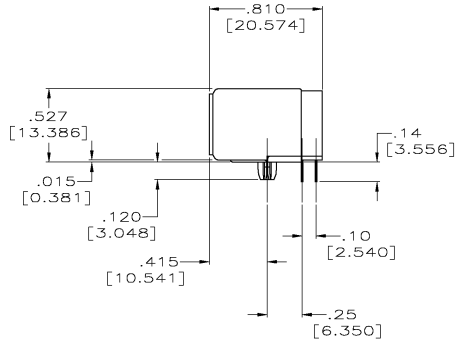
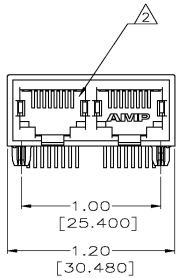
3

2

1

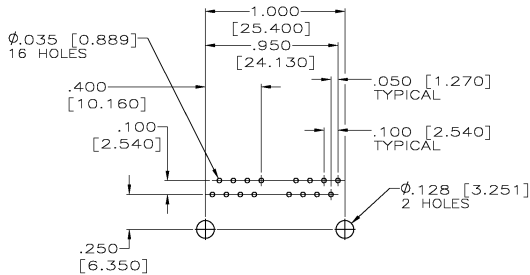
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LOC	QTY	REV	DESCRIPTION	DATE	BY	APP
AA	22	A	ECDS11-0201-04	25MAY2005	LAM	SF

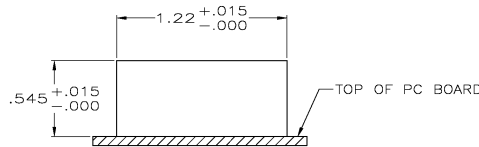


- MATERIAL: HOUSING - HTN NYLON, BLACK, IR REFLOW PROCESSING COMPATIBLE, UL 94V-0. TERMINALS - .013[0.33] THICK PHOS BRONZE PLATED WITH .000050[1.27µm] THICK HARD GOLD IN LOCALIZED AREA AND .000150[3.81µm] THICK MATTE TIN IN SOLDER AREA OVER .000050[1.27µm] THICK NICKEL UNDERPLATE.

- △ JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
- 4. ALL DIMENSIONS SHOWN IN BRACKETS [ ] ARE IN MILLIMETERS.



SUGGESTED PC BOARD LAYOUT  
 COMPONENT SIDE  
 SEE APPLICATION SPECIFICATION



SUGGESTED PANEL CUTOUT

5557560-1  
 PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DN: V. SLACK/L. A. MAYER CHK: J. WESTMAN	25MAY2005 25MAY2005	<b>tyco</b> <b>Electronics</b>	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
DIMENSIONS: INCHES	TOLERANCE UNLESS OTHERWISE SPECIFIED	APPRO: S. ELKESINGER	NAME: 108-1392	MODULAR JACK ASSEMBLY, TWO PORT, 8 POSITION, RIGHT ANGLE	
0 P.L.C. ±	1 P.L.C. ±	2 P.L.C. ±	3 P.L.C. ±	4 P.L.C. ±	ANGLES ±
SEE NOTE 1	SEE NOTE 1	APPLICATION SPEC: 114-2048	HEIGHT: -	SIZE: A2	DATE CODE: 00779
MATERIAL FINISH	SEE NOTE 1	CUSTOMER DRAWING	SCALE: 2:1	SHEET: 1 OF 1	REV: A